Expandable and settable deployable preform containing unsaturated resins, use for casing of wells or canalisation

Patent number:

EP1125965

Publication date:

2001-08-22

Inventor:

MARIAGGI PAUL (FR); AUDIGIER DOMINIQUE (FR);

HAUVILLER FREDERIQUE (FR)

Applicant:

INST FRANÇAIS DU PETROL (FR)

Classification:

- international:

C08J5/00

- european:

C08J3/24; C08J5/00; E21B17/00; E21B43/10F

Application number: EP20010400235 20010130 Priority number(s): FR2000001617 20000208 Also published as:

US6824847 (B2) US2001020053 (A1)

FR2804686 (A1)

CA2334496 (A1)

EP1125965 (B1)

Cited documents:

US5436396 FR2753978

EP0542584

US5348084 GB2063888

more >>

Report a data error here

Abstract not available for EP1125965

Abstract of corresponding document: US2001020053

A radially deployable flexible preform which, after deploying, forms a tubular structure that is curable by polymerization after positioning it in a well or in a line and moulds to the shape thereof after curing, comprises in its constitution at least one resin comprising in its chemical formula, at least one reactive multiple bond that is capable of subsequent reaction with compounds comprising in their constitution at least one terminal reactive multiple bond or a reactive multiple bond positioned at one end or the other of the molecular chain and/or on a pendant group. The long latent period heat curing resin has a glass transition temperature of at least 90 DEG C. and can be associated with at least one polymerisable oligomer and/or at least one monomer comprising at least one multiple bond in its chemical formulae. The resin can also be associated with drying reducers or flow regulators ensuring optimum retention of the fiber/matrix ratio during pressing occurring on deployment of the expandable preform. These compositions optionally comprise post-polymerization shrinkage reducers. Normally, an unsaturated polyester resin or a vinyl ester resin is used, or a mixture of resins usually containing at least one of these resins.

Data supplied from the esp@cenet database - Worldwide